

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

1-14. (canceled)

15. (currently amended) A method for fabricating a semiconductor wafer with a contact point comprising gold, comprising:

ion milling ~~cleaning~~ said contact point, and

~~after said cleaning said contact point, testing said semiconductor wafer by using a testing element contacting said contact point.~~

Claim 16 (canceled)

17. (currently amended) The method of claim 15, wherein said ion milling ~~cleaning~~ said contact point comprises ~~ion milling with~~ using argon.

Claims 18-26. (canceled)

27. (currently amended) A method for fabricating a semiconductor wafer, comprising:

depositing a bump on a topmost patterned circuit layer of said semiconductor wafer, wherein said bump has a substantially flat top surface; and ~~comprises a pillar-shaped portion;~~

ion milling cleaning said bump; and

~~after said cleaning said bump, testing said semiconductor wafer by using a testing element contacting said bump.~~

Claims 28 and 29. (canceled)

30. (currently amended) The method of claim 27, wherein said ion milling cleaning said bump comprises ~~ion milling with~~ using argon.

Claims 31-34. (canceled)